

TPC8227-H

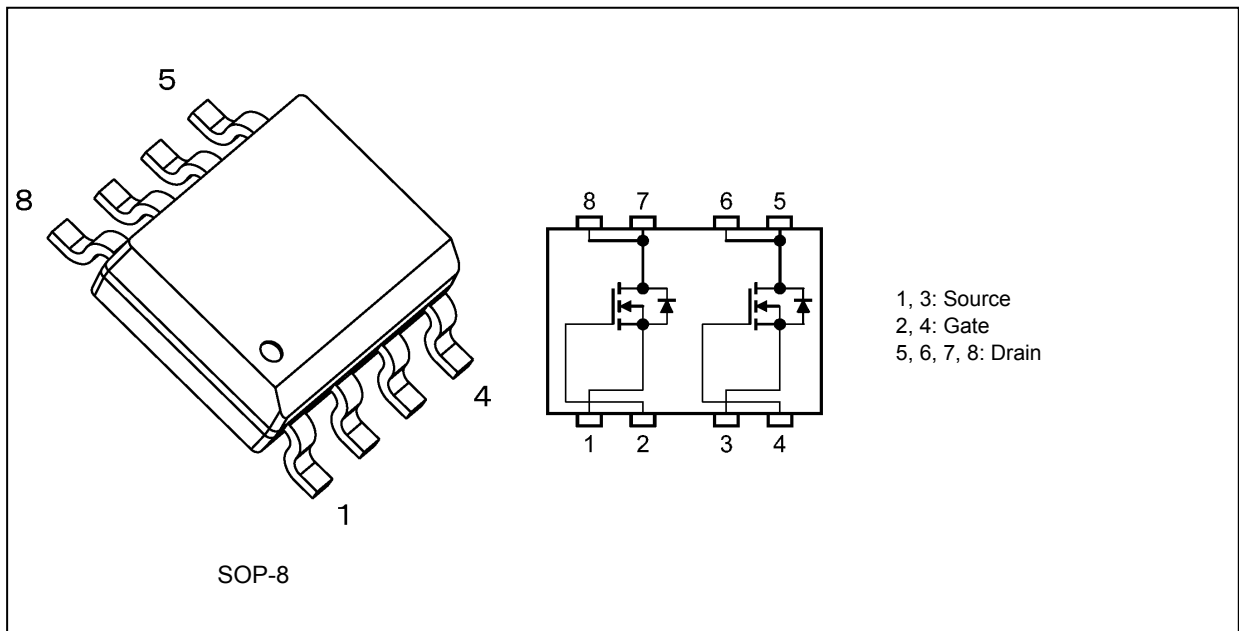
1. Applications

- DC-DC Converters
- CCFL Inverters

2. Features

- (1) Small, thin package
- (2) High-speed switching
- (3) Small gate charge: $Q_{SW} = 2.4 \text{ nC (typ.)}$
- (4) Low drain-source on-resistance: $R_{DS(ON)} = 22 \text{ m}\Omega \text{ (typ.)}$
- (5) Low leakage current: $I_{DSS} = 10 \text{ }\mu\text{A (max) (}V_{DS} = 40 \text{ V)}$
- (6) Enhancement mode: $V_{th} = 1.3 \text{ to } 2.3 \text{ V (}V_{DS} = 10 \text{ V, } I_D = 0.1 \text{ mA)}$

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	40	V
Gate-source voltage	V_{GSS}	± 20	
Drain current (DC) (Note 1)	I_D	5.1	A
Drain current (pulsed) (Note 1)	I_{DP}	20.4	
Power dissipation (single operation) (t = 10 s) (Note 2), (Note 4)	$P_{D(1)}$	1.5	W
Power dissipation (per device for dual operation) (t = 10 s) (Note 2), (Note 5)	$P_{D(2)}$	1.1	
Power dissipation (single operation) (t = 10 s) (Note 3), (Note 4)	$P_{D(1)}$	0.75	
Power dissipation (per device for dual operation) (t = 10 s) (Note 3), (Note 5)	$P_{D(2)}$	0.45	
Single-pulse avalanche energy (Note 6)	E_{AS}	24	mJ
Avalanche current	I_{AR}	5.1	A
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-ambient thermal resistance (single operation) (t = 10 s) (Note 2), (Note 4)	$R_{th(ch-a)(1)}$	83.3	$^\circ\text{C}/\text{W}$
Channel-to-ambient thermal resistance (per device for dual operation) (t = 10 s) (Note 2), (Note 5)	$R_{th(ch-a)(2)}$	113	
Channel-to-ambient thermal resistance (single operation) (t = 10 s) (Note 3), (Note 4)	$R_{th(ch-a)(1)}$	166	
Channel-to-ambient thermal resistance (per device for dual operation) (t = 10 s) (Note 3), (Note 5)	$R_{th(ch-a)(2)}$	277	

Note 1: Ensure that the channel temperature does not exceed 150°C .

Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4: Power dissipation and thermal resistance values per device with the other device being off (During single operation, power is supplied to only one of the two devices.)

Note 5: Power dissipation and thermal resistance values per device for dual operation (During dual operation, power is evenly supplied to both devices.)

Note 6: $V_{DD} = 24\text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 1.0\text{ mH}$, $I_{AR} = 5.1\text{ A}$

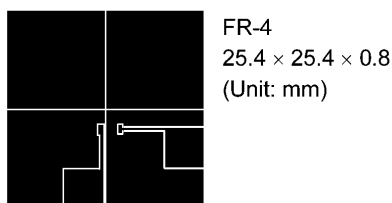


Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

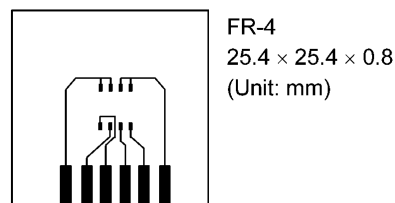


Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

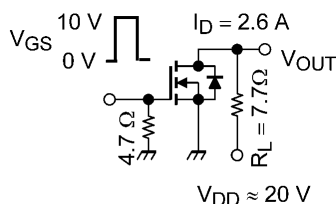
6.1. Static Characteristics ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	I_{GSS}	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 0.1	μA
Drain cut-off current	I_{DSS}	$V_{DS} = 40\text{ V}, V_{GS} = 0\text{ V}$	—	—	10	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	40	—	—	V
Drain-source breakdown voltage (Note 7)	$V_{(BR)DSX}$	$I_D = 10\text{ mA}, V_{GS} = -20\text{ V}$	23	—	—	
Gate threshold voltage	V_{th}	$V_{DS} = 10\text{ V}, I_D = 0.1\text{ mA}$	1.3	—	2.3	
Drain-source on-resistance	$R_{DS(ON)}$	$V_{GS} = 4.5\text{ V}, I_D = 2.6\text{ A}$	—	26	40	$\text{m}\Omega$
		$V_{GS} = 10\text{ V}, I_D = 2.6\text{ A}$	—	22	33	

Note 7: If a reverse bias is applied between gate and source, this device enters $V_{(BR)DSX}$ mode. Note that the drain-source breakdown voltage is lowered in this mode.

6.2. Dynamic Characteristics ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input capacitance	C_{iss}	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	640	—	pF
Reverse transfer capacitance	C_{rss}		—	35	—	
Output capacitance	C_{oss}		—	115	—	
Gate resistance	r_g	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 5\text{ MHz}$	—	3.2	4.6	Ω
Switching time (rise time)	t_r	See Figure 6.2.1.	—	1.7	—	ns
Switching time (turn-on time)	t_{on}		—	6.7	—	
Switching time (fall time)	t_f		—	1.9	—	
Switching time (turn-off time)	t_{off}		—	17	—	



Duty $\leq 1\%$, $t_w = 10\ \mu\text{s}$

Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx 32\text{ V}, V_{GS} = 10\text{ V}, I_D = 5.1\text{ A}$	—	10	—	nC
		$V_{DD} \approx 32\text{ V}, V_{GS} = 5\text{ V}, I_D = 5.1\text{ A}$	—	5.3	—	
Gate-source charge 1	Q_{gs1}	$V_{DD} \approx 32\text{ V}, V_{GS} = 10\text{ V}, I_D = 5.1\text{ A}$	—	2.0	—	
Gate-drain charge	Q_{gd}		—	1.5	—	
Gate switch charge	Q_{sw}		—	2.4	—	

6.4. Source-Drain Characteristics ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Reverse drain current (pulsed) (Note 8)	I_{DRP}	—	—	—	20.4	A
Diode forward voltage	V_{DSF}	$I_{DR} = 5.1 \text{ A}, V_{GS} = 0 \text{ V}$	—	—	-1.2	V

Note 8: Ensure that the channel temperature does not exceed 150°C .

7. Marking (Note)

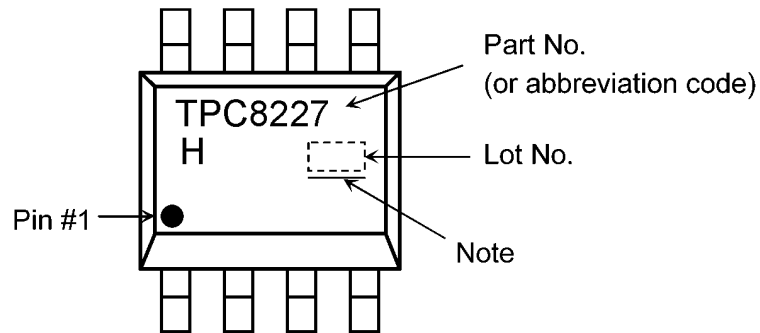


Fig. 7.1 Marking

Note: A line under a Lot No. identifies the indication of product Labels.

Not underlined: $[[Pb]]/INCLUDES > MCV$

Underlined: $[[G]]/RoHS \text{ COMPATIBLE}$ or $[[G]]/RoHS [[Pb]]$

Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

8. Characteristics Curves (Note)

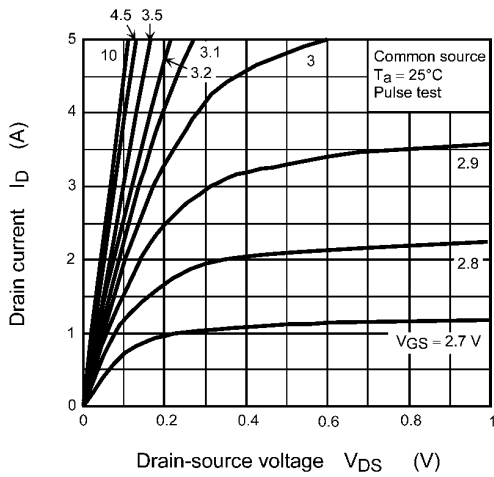


Fig. 8.1 $I_D - V_{DS}$

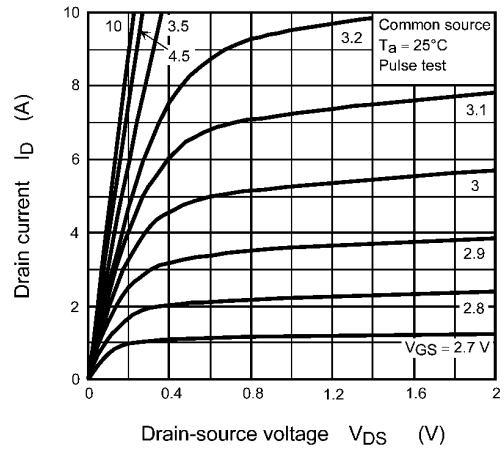


Fig. 8.2 $I_D - V_{DS}$

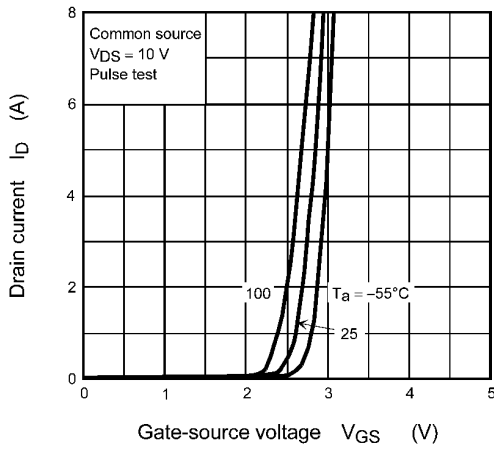


Fig. 8.3 $I_D - V_{GS}$

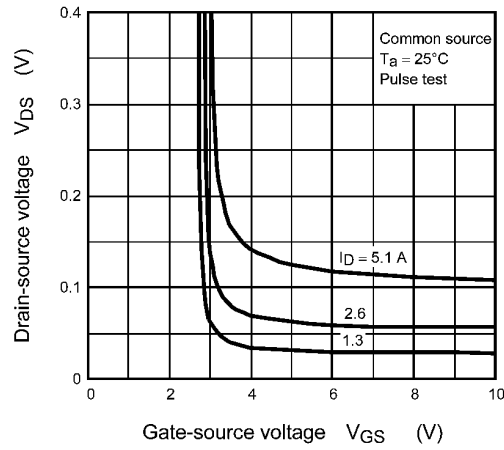


Fig. 8.4 $V_{DS} - V_{GS}$

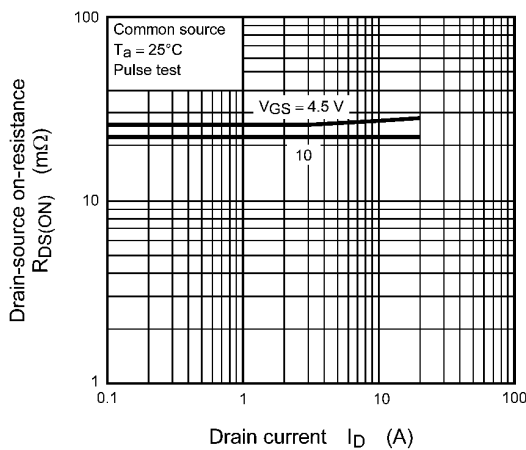


Fig. 8.5 $R_{DS(ON)} - I_D$

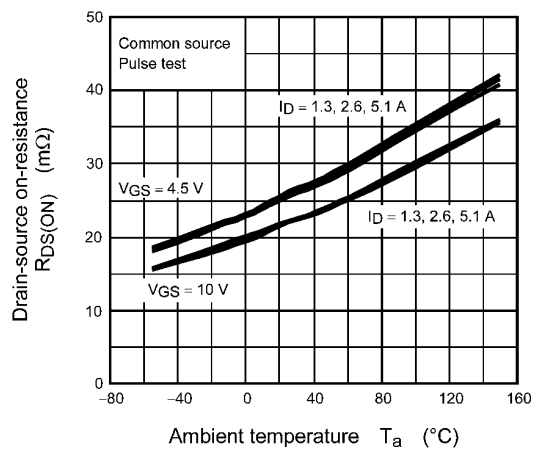


Fig. 8.6 $R_{DS(ON)} - T_a$

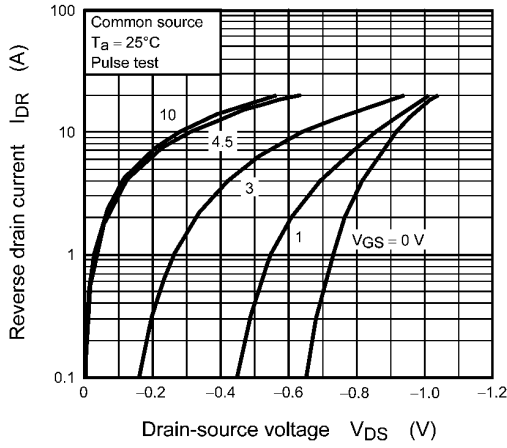


Fig. 8.7 $I_{DR} - V_{DS}$

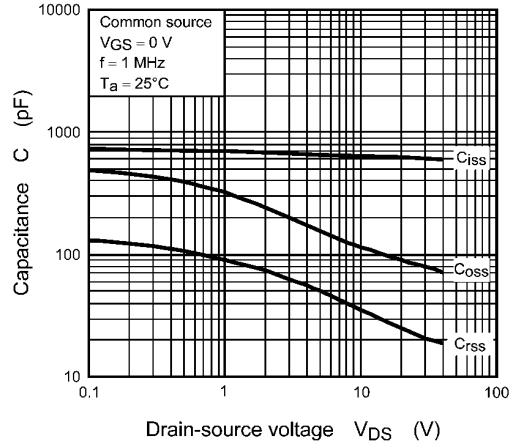


Fig. 8.8 Capacitance - V_{DS}

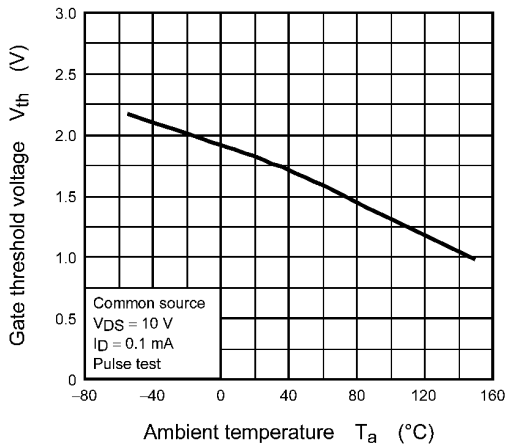


Fig. 8.9 $V_{th} - T_a$

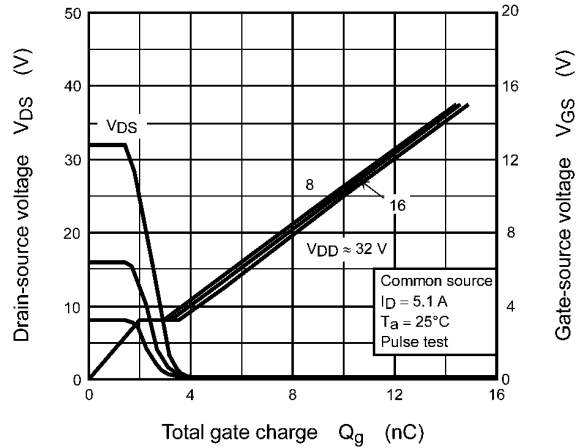


Fig. 8.10 Dynamic Input/Output Characteristics

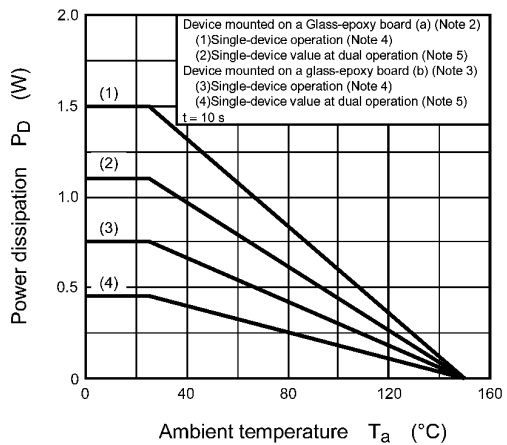


Fig. 8.11 $P_D - T_a$
 (Guaranteed Maximum)

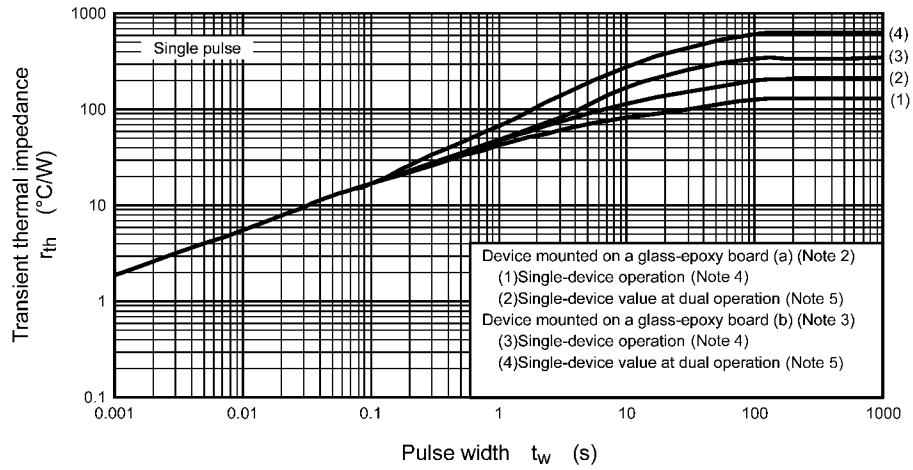


Fig. 8.12 $r_{th} - t_w$
(Guaranteed Maximum)

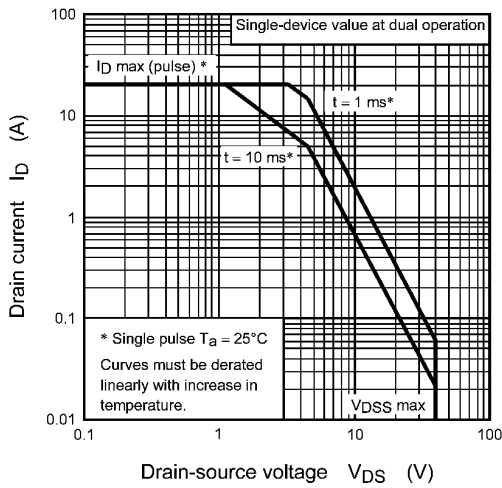
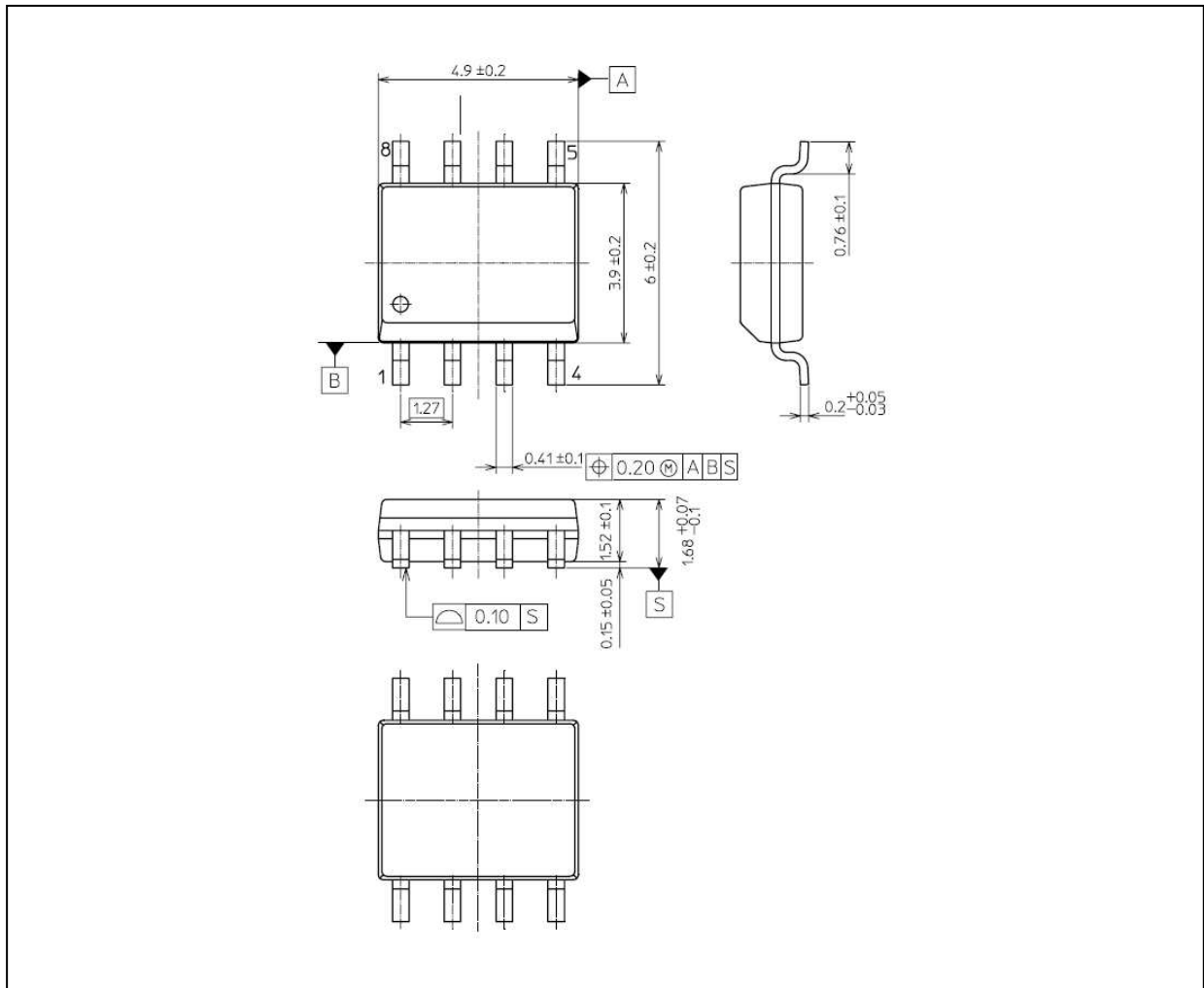


Fig. 8.13 Safe Operating Area
(Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 0.085 g (typ.)

Package Name(s)
TOSHIBA: 2-5R1S
Nickname: SOP-8

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